

I. Amendments to the Specification

Please replace paragraph [0010] with the following new paragraph:

[0010] In accordance with the preferred embodiment of this invention, referring to Figures 1-3, a microelectronic package 10 comprises a microelectronic assembly 12 received in a tubular housing 14. Housing 14 is preferably formed of metal and is cylindrical about an axis 16, such that an inner wall 18 circumferentially surrounds assembly 12. By way of a preferred example, housing 14 may be a segment of a casing of a missile. While in Figure 1, housing 14 is depicted as having a length similar to assembly 12, housing 14 may be axially extended to include space for containing additional components such as batteries, gyroscopic components, motors or radiance.